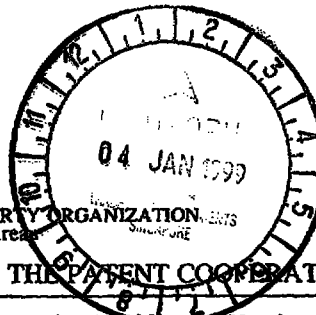


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(54) Title: HEAT ABLATIVE COATING COMPOSITION (57) Abstract A heat ablative coating composition is prepared by combining an epoxy silane resin, an epoxy resin, a silicone intermediate, a silicon-modified polyether, an aminosilane, at least one organometallic catalyst, at least one organic solvent, water, at least one filler, optional nonsilicon-containing amine catalyst, and optional pigments and thixotropic agents. The heat ablative coating composition is applied to a substrate to form a film having a build thickness in the range of from about 0.1 to 0.5 inches that is capable of curing at ambient outdoor temperature in about seven days, depending on ambient conditions. The heat ablative film so formed is designed to undergo a slow thermal decomposition when exposed to high temperature conditions without igniting or causing excessive smoke, and is designed to have good thermal conductivity to protect the underlying substrate from thermal decomposition. The heat ablative film has elastomeric properties of impact resistance and flexibility that serves to both protect an underlying structure from mechanical damage due to particle or other contact, and facilitate its use with flexible substrates.		